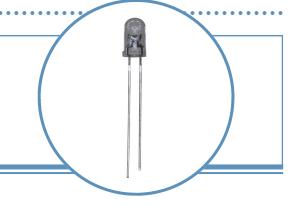
Round Through-Hole LED Lamp (5 mm)



OVLFx3C7 Series

- · High brightness with well-defined spatial radiation patterns
- UV-resistant epoxy lens
- Blue, green, red, yellow

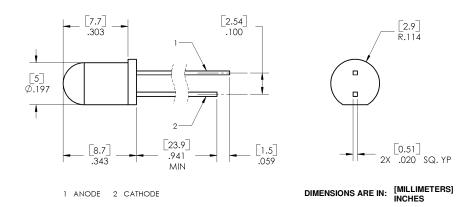


Each device in the **OVLFx3C7** series is a high-intensity LED mounted in a clear plastic T-1¾ package. The LED provides a well-defined and even emission pattern. Its UV-resistant epoxy lens makes this device an optimal solution for outdoor applications.

Applications

- Traffic and pedestrian signals
- Signage and architectural lighting
- Backlighting
- Automotive

Part Number	Material	Emitted Color	Intensity Typ. mcd	Lens Color
OVLFB3C7	InGaN	Blue	2000	Water Clear
OVLFG3C7	InGaN	Green	7000	Water Clear
OVLFR3C7	AllnGaP	Red	5000	Water Clear
OVLFY3C7	AllnGaP	Yellow	4000	Water Clear





Leadframe material is iron alloy with tin-plated leads

DO NOT LOOK DIRECTLY AT LED WITH UNSHIELDED EYES OR DAMAGE TO RETINA MAY OCCUR.



Absolute Maximum Ratings T_A = 25° C unless otherwise noted

Storage Temperature Range		-40 ~ +100 ℃
Operating Temperature Range		-40 ~ +85 ℃
Reverse Voltage		5 V
Continuous Forward Current	Blue, Green	20 mA
Continuous Forward Current	Red, Yellow	30 mA
Dook Forward Current (100/ Duty Cycle 1 kHz)	Blue, Green	50 mA
Peak Forward Current (10% Duty Cycle, 1 kHz)	Red, Yellow	100 mA
Dawer Dissination	Blue, Green	80 mW
Power Dissipation	Red, Yellow	72 mW
Comment Linearity on Ambient Temperature	Blue, Green	-0.2 mA/° C
Current Linearity vs Ambient Temperature	Red, Yellow	-0.5 mA/° C
LED Junction Temperature		125° C
Lead Soldering Temperature (4 mm from the base of the epoxy	bulb)	260°C/5 seconds

Electrical Characteristics

 $T_A = 25^{\circ} C$ unless otherwise noted

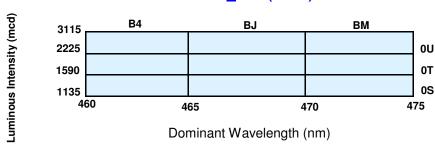
SYMBOL	PARAMETER	COLOR	MIN	TYP	MAX	UNITS	CONDITIONS	
		Blue	1135	2000				
	Luminous Intensity	Green	4360	7000		mad	J 00 A	
I _V		Red	2820	5000		mcd	$I_F = 20 \text{ mA}$	
		Yellow	2225	4000				
		Blue		3.4	4.0			
V_{F}	Forward Voltage	Green	2.6	3.4	4.0	V	I _ 20 m A	
٧ _F	Forward Voltage	Red		2.0	2.4	v	$I_F = 20 \text{ mA}$	
		Yellow		2.0	2.4			
I _R	Reverse Current	Blue			50	μΑ		
		Green			50		V _R = 5 V	
		Red			10			
		Yellow			10			
		Blue	460	465	475			
ì	Dominant Wayalangth	Green	519	525	531	nm	1 20 m A	
λ_{D}	Dominant Wavelength	Red	620	625	630		$I_F = 20 \text{ mA}$	
		Yellow	585	589	595			
	Spectra Half Width	Blue		25		nm		
Δλ		Green		25			I _F = 20 mA	
		Red		25			IF = ZU IIIA	
		Yellow		25				
2Θ½H-H	50% Power Angle			30		deg	I _F = 20 mA	



Standard Bins (I_F = 20 mA)

Lamps are sorted to luminous intensity (I_V) and dominant wavelength (λ_D) bins shown. Orders may be filled with any or all bins contained as below.

OVLFB3C7 (BLUE)



Forward Voltage (V_F)

Rank	Н	J	K	L
Voltage	2.6–3.0	3.0-3.3	3.3–3.6	3.6-4.0

OVLFG3C7 (GREEN)



Dominant Wavelength (nm)

Forward Voltage (V_F)

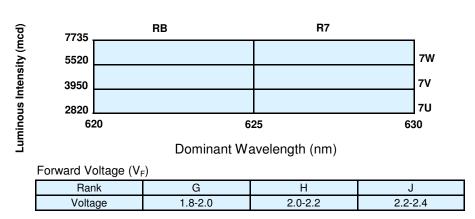
Rank	Н	J	K	L		
Voltage	2.6-3.0	3.0-3.3	3.3-3.6	3.6-4.0		

Notes:

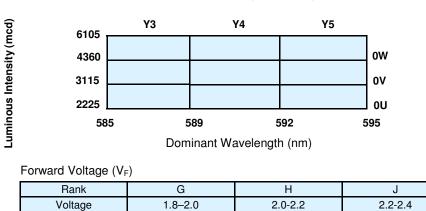
- 1. All ranks will be included per delivery, rank ratio will be based on the chip distribution.
- 2. To designate luminous intensity ranks, please contact OPTEK.
- 3. Pb content <1000 PPM.



OVLFR3C7 (RED)



OVLFY3C7 (YELLOW)

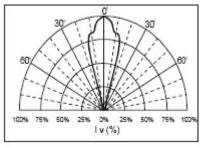


Important Notes:

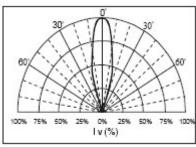
- 1. All ranks will be included per delivery, rank ratio will be based on the chip distribution.
- To designate luminous intensity ranks, please contact OPTEK.
- 3. Pb content <1000 PPM.

Beam Pattern

(RED) and (YELLOW)

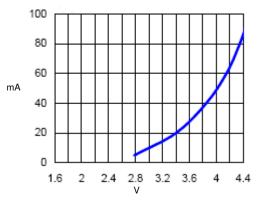


(BLUE) and (GREEN)

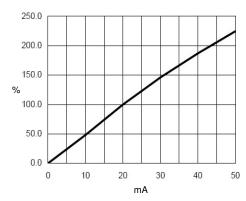




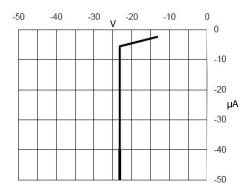
Typical Electro-Optical Characteristics Curves (BLUE)



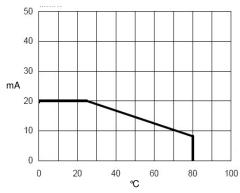
Forward Current vs Forward Voltage



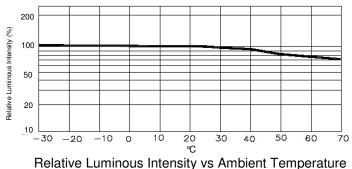
Relative Luminous Intensity vs Forward Current

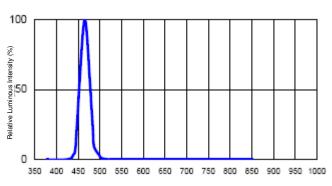


Reverse Current vs Reverse Voltage



Forward Current vs Ambient Temperature

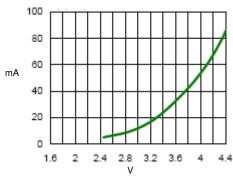




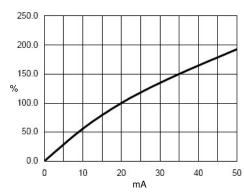
Relative Luminous Intensity vs. Wavelength



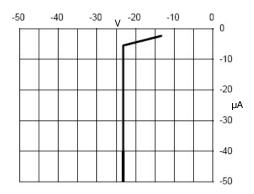
Typical Electro-Optical Characteristics Curves (GREEN)



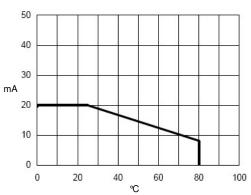
Forward Current vs Forward Voltage



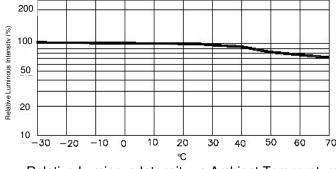
Relative Luminous Intensity vs Forward Current



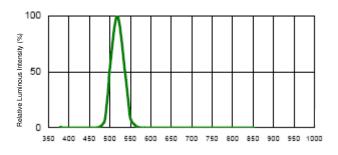
Reverse Current vs Reverse Voltage



Forward Current vs Ambient Temperature



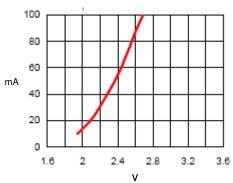
Relative Luminous Intensity vs Ambient Temperature



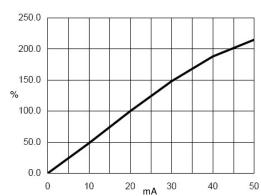
Relative Luminous Intensity vs. Wavelength



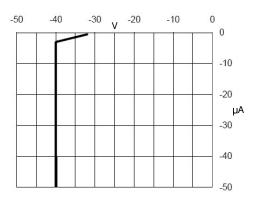
Typical Electro-Optical Characteristics Curves (RED)



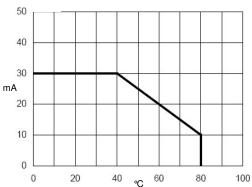
Forward Current vs Forward Voltage



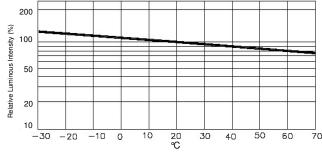
Relative Luminous Intensity vs Forward Current



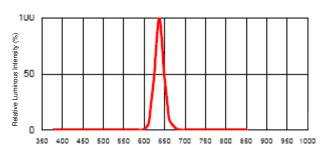
Reverse Current vs Reverse Voltage



Forward Current vs Ambient Temperature



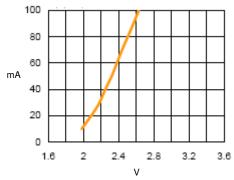
Relative Luminous Intensity vs Ambient Temperature



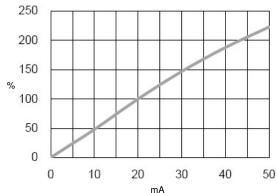
Relative Luminous Intensity vs. Wavelength



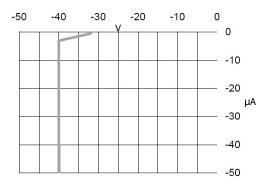
Typical Electro-Optical Characteristics Curves (YELLOW)



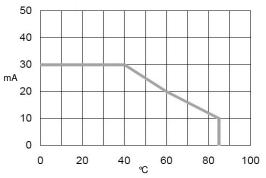
Forward Current vs Forward Voltage



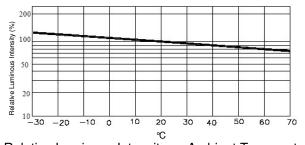
Relative Luminous Intensity vs Forward Current



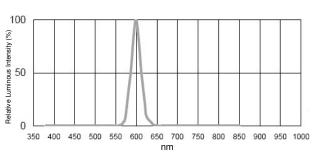
Reverse Current vs Reverse Voltage



Forward Current vs Ambient Temperature



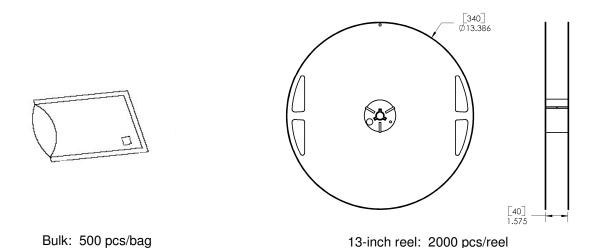
Relative Luminous Intensity vs Ambient Temperature



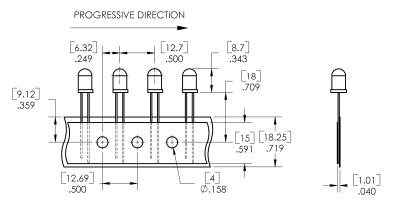
Relative Luminous Intensity vs Wavelength



Packing Information: Available in bulk or tape/reel

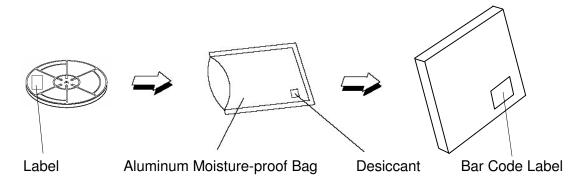


Carrier Tape Dimensions: Loaded quantity 2000 pieces per reel



DIMENSIONS ARE IN INCHES AND [MILLIMETERS].

Moisture Resistant Packaging





Reliability Test

LED lamps are checked by reliability tests based on MIL standards.

					_	
Test Item	Standard Test Method	Test Conditions	Duration	Unit	Acc / Rej Criteria	Result
peration Life Test	MIL-STD-750D	T -25°C + I -30m A *	1000 Ues	100	0 / 1	Pass
(OLT)	Method 1026.3	1 _A -25 C / I _F -50mA	1000 His	100	071	Pass
High Temperature	MIL-STD-750D	T -100°C	1000 Hrs	100	0./1	Pass
Storage (HTS)	Method 1032.1	1A-100 C			071	
Low Temperature	MIL-STD-750D	T40°C	1000 Ues	100	0 / 1	Pass
Storage (LTS)	Method 1032.1	1 _A 40 C	1000 Hrs	100		
emp. & Humidity	MIL-STD-750D	T -95°C . Ph-9504 I -20m A **	500 Hrs	100	0 / 1	Pass
with Bias (THB)	Method 103B	1 _A -65 (7 Kii-6576 1 _F -2011A **				
Thermal Shock	MIL-STD-750D	0°C ~ 100°C	100	100	0 / 1	Pass
Γest (TST)	Method 1056.1	2min 2min	cycles	100	0/1	Pass
Temperature	MIL-STD-750D	-40°C ~ 25°C~ 100°C ~ 25°C	100	100	0./1	
Cycling Test (TCT)	Method 1051.5	30min 5min 30min 5min	cycles	100	0/1	Pass
Solderability	MIL-STD-750D	235±5°C → 5 sec	1 time	20	0 / 1	Pass
	Method 2026.4					
Resistance to	MIL-STD-750D	26015°C - 10	1	20	0./1	
Soldering Heat	Method 2031.1	200±3 (' 10 sec	1 time 20	20	0 / 1	Pass
	MIL-STD-750D	Load 2.5N (0.25kgf)	3 times	20	0 / 1	Pass
Lead Integrity	Method 2036.3	0°~90°~0°, bend				
E S E S E S E S E	Deration Life Test (OLT) Tigh Temperature torage (HTS) Tow Temperature torage (LTS) Town Temperature torage (LTS) Town Temperature torage (LTS) Town Temperature torage (LTS) Town Temperature Town Temperat	Test Item Test Method Deration Life Test (OLT) Method 1026.3 Righ Temperature MIL-STD-750D Method 1032.1 Dow Temperature MIL-STD-750D Method 1032.1 MIL-STD-750D Method 1032.1 MIL-STD-750D Method 103B Chermal Shock MIL-STD-750D Method 1056.1 Method 1056.1 Method 1051.5 MIL-STD-750D Method 1051.5 MIL-STD-750D Method 2026.4 MIL-STD-750D Method 2026.4 MIL-STD-750D Method 2031.1 MIL-STD-750D Method 2031.1 MIL-STD-750D	Test Item Test Method Test Conditions Peration Life Test (OLT) Method 1026.3 Tal Eigh Temperature MIL-STD-750D Method 1032.1 Town Temperature MIL-STD-750D Method 1032.1 Town Temperature MIL-STD-750D Method 1032.1 Tal Eigh Temperature MIL-STD-750D Method 1038 Tal Eigh Temperature MIL-STD-750D Method 1038 Tal Eigh Temperature MIL-STD-750D Method 1056.1 Tal Eigh Temperature MIL-STD-750D Method 2026.4 Tal Eigh Temperatu	Test Item Test Method Duration Test Conditions Duration Duration Test Conditions Test Conditions Duration Test Conditions Te	Test Item Test Method Test Conditions Duration Unit Decration Life Test (OLT) MIL-STD-750D (Method 1026.3) $T_A=25^{\circ}\text{C} \cdot I_F=30\text{mA} \cdot 8$ 1000 Hrs <	Test Item Test Method Test Conditions Duration Unit Criteria Decration Life Test (OLT) MIL-STD-750D (OLT) $T_A = 25^{\circ}\text{C} \cdot I_F = 30\text{mA} *$ 1000Hrs $100 \text{O} / 1$ Sigh Temperature (HTS) Mill-STD-750D (Method 1032.1) $T_A = 100^{\circ}\text{C}$ 1000Hrs $100 \text{O} / 1$ sow Temperature (HTS) Method 1032.1 $T_A = 40^{\circ}\text{C}$ 1000Hrs $100 \text{O} / 1$ sow Temperature (LTS) Method 1032.1 $T_A = 40^{\circ}\text{C}$ 1000Hrs $100 \text{O} / 1$ mp. & Humidity (HIL-STD-750D (LTS) Method 103B $T_A = 85^{\circ}\text{C} \cdot \text{Rh} = 85\% I_F = 20\text{mA} ** 500 \text{Hrs} 100 \text{O} / 1 thermal Shock (HTS) Mill-STD-750D (Method 1056.1) 0^{\circ}\text{C} \sim 100^{\circ}\text{C} \sim 25^{\circ}\text{C} \sim 100^{\circ}\text{C} \sim 25^{\circ}\text{C} 100 \text{O} / 1 0^{\circ}\text{C} \sim 100^{\circ}\text{C} \sim 100^{\circ}\text{C} \sim 25^{\circ}\text{C} \sim 100^{\circ}\text{C} $

Remark : (*) I_F =30mA for AlInGaP chip ; I_F =20mA for InGaN chip

(**) I_{F} =20mA for AlInGaP chip $\,\,;\,\,I_{F}$ =10mA for InGaN chip

2. Failure Criteria (T_A =25°C):

Test Item	Symbol	Test Conditions	Criteria for Judgment			
rest item	Symoor	rest conditions	Min.	Max.		
Luminous Intensity	$I_{ m V}$	I _F =20 mA	LSL×0.7 **			
Voltage (Forward)	V _F	I _F =20 mA		USL×1.1 *		

(*) USL: Upper Standard Level , (**) LSL: Lower Standard Level